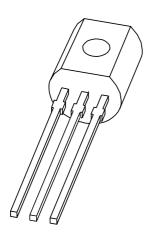
DISCRETE SEMICONDUCTORS

DATA SHEET



BF199NPN medium frequency transistor

Product data sheet Supersedes data of 1997 Jul 07 2004 Nov 08



NXP Semiconductors Product data sheet

NPN medium frequency transistor

BF199

FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 25 V).

APPLICATIONS

• Output stage of a vision IF amplifier.

DESCRIPTION

NPN medium frequency transistor in a TO-92; SOT54 plastic package.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector

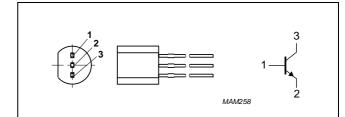


Fig.1 Simplified outline (TO-92; SOT54) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	PARAMETER CONDITIONS		TYP.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	_	40	V
V_{CEO}	collector-emitter voltage	open base	_	-	25	V
I _{CM}	peak collector current		_	_	25	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	_	_	500	mW
h _{FE}	DC current gain	V _{CE} = 10 V; I _C = 7 mA	38	_	_	
f _T	transition frequency	$V_{CE} = 10 \text{ V}; I_{C} = 5 \text{ mA}; f = 100 \text{ MHz}$	_	550	_	MHz

ORDERING INFORMATION

TVDE NUMBER	PACKAGE					
TYPE NUMBER NAME		DESCRIPTION	VERSION			
BF199	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54			

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	40	V
V_{CEO}	collector-emitter voltage	open base	_	25	V
V _{EBO}	emitter-base voltage	open collector	_	4	V
I _C	collector current (DC)		-	25	mA
I _{CM}	peak collector current		_	25	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	500	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	250	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector-base cut-off current	$V_{CB} = 40 \text{ V}; I_{E} = 0 \text{ A}$	_	_	100	nA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 4 \text{ V}; I_{C} = 0 \text{ A}$	_	_	100	nA
h _{FE}	DC current gain	$V_{CE} = 10 \text{ V}; I_{C} = 7 \text{ mA}$	38	_	_	
V_{BE}	base-emitter voltage	$V_{CE} = 10 \text{ V}; I_{C} = 7 \text{ mA}$	_	775	925	mV
C_{re}	feedback capacitance	$V_{CB} = 10 \text{ V}; I_C = 0 \text{ A}; f = 1 \text{ MHz}$	_	_	0.5	pF
f _T	transition frequency	$V_{CE} = 10 \text{ V}; I_{C} = 5 \text{ mA}; f = 100 \text{ MHz}$	_	550	_	MHz

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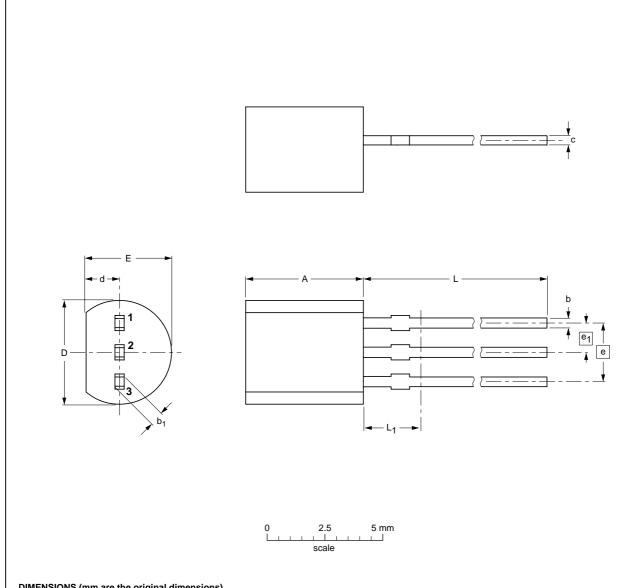
NPN medium frequency transistor

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PACKAGE OUTLINE

Plastic single-ended leaded (through hole) package; 3 leads

SOT54



DIMENSIONS (mm are the original dimensions)

UNIT	Α	b	b ₁	С	D	d	E	е	e ₁	L	L ₁ ⁽¹⁾ max.	
mm	5.2 5.0	0.48 0.40	0.66 0.55	0.45 0.38	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		EUROPEAN	ISSUE DATE			
VERSION IEC		JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT54		TO-92	SC-43A			04-06-28 04-11-16

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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